

JMA100R160NP

General Description

- Low R_{DS(on)} & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery

Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Product Summary



| VDS | 100 | V |
|------------------------|-----|----|
| R DS(on),Typ@ VGS=10 V | 12 | mΩ |
| / D | 45 | А |





Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

| Parameter | | Symbol | Limit | Unit | |
|--|----------------------|----------------------------------|----------|------|--|
| Drain-source Voltage | | V _{DS} | 100 | V | |
| Gate-source Voltage | | V _{GS} | ±20 | V | |
| Drain Current | T _C =25℃ | | 45 | A | |
| | T _C =100℃ | ID | 28.5 | | |
| Pulsed Drain Current ^A | | I _{DM} | 180 | А | |
| Avalanche energy ^B | | Eas | 81 | mJ | |
| Total Power Dissipation ^c | Tc=25 ℃ | P | 72 | 10/ | |
| | Tc=100℃ | FD | 28.8 | vv | |
| Junction and Storage Temperature Range | | T _J ,T _{STG} | -55~+150 | °C | |

Thermal resistance

| Parameter | Symbol | Тур | Мах | Units | |
|--|--------------|-----------------------|------|-------|------|
| Thermal Resistance Junction-to-Ambient D | t≪10S | P | 15 | 20 | |
| Thermal Resistance Junction-to-Ambient D | Steady-State | | 40 | 50 | °C/W |
| Thermal Resistance Junction-to-Case | Steady-State | $R_{	extsf{	heta}JC}$ | 1.35 | 1.7 | |

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Electrical Characteristics (T_i=25°C unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Тур | Max | Units |
|---------------------------------------|---------------------|---|-----|------|------|-------|
| Static Parameter | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V_{GS} = 0V, I _D =250µA | 100 | | | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =100,V _{GS} =0V | | | 1 | μA |
| Gate-Body Leakage Current | I _{GSS} | $V_{GS}\text{=}\pm20V\text{, }V_{DS}\text{=}0V$ | | | ±100 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V_{DS} = V_{GS} , I_D =250 μ A | 1 | 1.7 | 3 | V |
| Static Drain Source On Posiciance | | V _{GS} = 10V, I _D =20A | | 12 | 17 | mΩ |
| | RDS(ON) | V _{GS} = 4.5V, I _D =20A | | 17 | 21.5 | mΩ |
| Diode Forward Voltage | V_{SD} | I _S =20A,V _{GS} =0V | | | 1.3 | V |
| Maximum Body-Diode Continuous Current | Is | | | | 45 | А |
| Gate resistance | R_{G} | f= 1 MHz, Open drain | | 1 | | Ω |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C _{iss} | | | 1064 | | |
| Output Capacitance | C _{oss} | V _{DS} =50V,V _{GS} =0V,f=1MHZ | | 374 | | pF |
| Reverse Transfer Capacitance | C _{rss} | | | 17 | | |
| Switching Parameters | | | | | | |
| Total Gate Charge | Qg | | | 16 | | |
| Gate-Source Charge | Q_gs | $V_{GS}=10V, V_{DS}=50V, I_{D}=25A$ | | 5.6 | | 20 |
| Gate-Drain Charge | Q_{gd} | | | 2.4 | | nc |
| Reverse Recovery Chrage | Q _{rr} | I _F =20A, di/dt=100A/us | | 42 | | |
| Reverse Recovery Time | t _{rr} | | | 39.8 | | |
| Turn-on Delay Time | t _{D(on)} | Ves=10V. Vpp=50V.lp=25A | | 39.2 | | |
| Turn-on Rise Time | tr | | | 11 | | ns |
| Turn-off Delay Time | $t_{D(off)}$ | R _{GEN} =2.2Ω | | 53.2 | | |
| Turn-off fall Time | t _f | | | 15.8 | | |

Repetitive rating; pulse width limited by max. junction temperature. V_{DD} =50V, R_{G} =25 Ω , L=0.5mH, I_{AS}=25A,. Α.

В.

Pd is based on max. junction temperature, using junction-case thermal resistance. C.

The value of RqJA is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with TA =25°C. The D. Power dissipation PDSM is based on R qJA t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.







Typical Performance Characteristics

Figure 1. Output Characteristics



Figure3. Capacitance Characteristics



Figure5. : On-Resistance vs. Drain Current and Gate Voltage



Figure2. Transfer Characteristics



Figure4. Gate Charge



Figure6.Normalized On-Resistance





Figure7. Drain current





Figure9.Normalized Maximum Transient thermal impedance



Ordering and Marking Information

| Ordering Device No. | Marking | Package | Packing | Quantity |
|---------------------|----------|---------|---------|----------|
| JMA100R160NP-T | 100R160N | TO-220 | Tube | 50/Tube |













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